

WE ARE HIRING

Senior Packaging Industrialization Engineer

San Jose, California, USA • Eindhoven, The Netherlands

Turn advanced silicon photonics packaging into a repeatable, high-volume manufacturing process.

Photon Bridge is developing a fundamentally new external laser architecture for AI datacenters. Our technology addresses one of the largest manufacturing bottlenecks in silicon photonics by enabling scalable, passive assembly of multi-wavelength laser engines.

We are moving from breakthrough technology to industrial reality, and we are looking for a senior packaging industrialization engineer who can bridge PIC design and factory execution.

Your mission

You will make sure our silicon photonics package can actually be built, controlled and scaled in high-volume factories.

You will sit between our PIC designers and external packaging partners: translating packaging constraints into PIC design requirements, and PIC constraints into clear, executable assembly specifications.

Our senior package design capability is already in place. Your focus is making that design manufacturable, transferable and scalable.

What success looks like

- PIC and package designs that are aligned from the start with real factory capabilities
- Clear assembly specifications, tolerances and process windows that packaging partners can execute
- Fast resolution of manufacturability issues during prototype builds and NPI
- A packaging process that progresses from engineering builds to stable, repeatable volume production

What you will own

Design-to-factory interface

- Act as the technical interface between PIC designers and packaging partners
- Translate packaging constraints into PIC design rules and requirements
- Translate PIC requirements into package, assembly and process specifications
- Drive DFM reviews across die, attach, alignment, interconnect and assembly

Industrialization and factory execution

- Work directly with packaging houses on process capability, tolerances, control plans and yield
- Support prototype builds, engineering lots, NPI and production ramp
- Identify manufacturability risks early and drive design or process changes before they become production issues
- Spend significant time at supplier factories to make sure execution matches design intent
- Drive issues to closure with internal teams and manufacturing partners

What you bring

Essential experience

- 8–15+ years of relevant industry experience in silicon photonics, optoelectronics, semiconductor or advanced packaging
- Direct experience working with packaging houses, OSATs or contract manufacturers
- Strong understanding of DFM, process capability, assembly tolerances, yield and NPI
- Enough technical depth to connect PIC design intent with real manufacturing constraints
- Proven ability to move sophisticated hardware from prototype builds toward scalable production

How you work

- Hands-on, detail-oriented and comfortable working on the factory floor
- Structured enough to create clarity, pragmatic enough to keep the program moving
- Able to challenge both designers and manufacturing partners constructively
- Naturally asks: Can this be built at volume? What will fail when we scale? What should we change now?

Reporting line: This role reports directly to the COO

Why Photon Bridge?

- Work on one of the defining packaging challenges in next-generation silicon photonics for AI infrastructure
- Have direct influence on both PIC design and the manufacturing process used to build the product
- Work closely with leading packaging partners and high-volume factories
- Make a visible impact on whether breakthrough photonics technology successfully scales to production

How to apply

Please submit your resume and a cover letter outlining your relevant experience and interest to jobs@photonbridge.com

Photon Bridge is committed to diversity and encourages applications from all qualified candidates from all backgrounds to apply.

Photon Bridge only works with pre-qualified recruitment agencies.